ON Semiconductor

Initial Product/Process Change Notification

Document # : IPCN21370X
Issue Date: 21 June 2016

Title of Change:	Qualification of High Frequency Voltage Regulation (HFVR) Gen1.0 Process in ON Semiconductor wafer fabrication facility in Niigata, Japan.
Proposed first ship date:	28 October 2016
Contact information:	Contact your local ON Semiconductor Sales Office or <Joe.Chong@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office.
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected first lot will be identified the date code which will be publish on the Final PCN notice.
Change category:	☒ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other ________________

Change Sub-Category(s):

☒ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: _________________________

Sites Affected:

☐ All site(s)
☐ not applicable
☒ ON Semiconductor site(s) :
ON Niigata, Japan
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☐ External Foundry/Subcon site(s)
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Description and Purpose:

The purpose of this Initial PCN is to notify customers of adding a new wafer fab location/ site for HFVR (High Frequency Voltage Regulation) Gen1.0 process/products.

The High Side FET of the affected part numbers is currently manufactured from Oudenaarde, Belgium. Once the qualification is completed, ON Semiconductor will produce the affected part number from Oudenaarde, Belgium and/or Niigata, Japan Wafer FAB Facilities.

Qualification Plan:

QV DEVICE NAME : NCP3231AMNTXG
PACKAGE: QFN 40 6*6

Test	Specification	Condition	Interval
HTRB	JESD22-A108	TA=150C, VDSS=22V	1008 hrs
HTGB	JESD22-A108	TA=150C, Bias = 8V	1008 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=25 C, Delta Tj = 100C max	15000 cyc
TC	JESD22-A104	Ta= -55°C to +150°C	500 cyc
H3TRB	JESD22-A101	TA = 85°C/85% RH	1008 hrs
HAST	JESD22-A110	130°C/85% RH	96 hrs
uHAST	JESD22-A118	130°C/85% RH	96 hrs

Estimated date for qualification completion: **29 July 2016**

List of Affected Standard Parts

Part Number	Qualification Vehicle
NCP3231AMNTXG	NCP3231AMNTXG
NCP3231MNTXG	NCP3231AMNTXG
NCP5339MNTXG	NCP3231AMNTXG